

Capability List (Rigid board)

Item		Technical Specification	
		Standard	Advanced
Number of Layers		1-30 layer	30-48 layer
Laminate		FR-4, CEM-3, High Tg, Halogen free, Aluminum Base, Teflon	Metclad, Thermount
Laminate Brand		KB, Shengyi, Nanya, Isola, Rogers, Arlon, Taconic	customer specify
Maximum board size		508X760mm	508x1060mm(double side only)
Board thickness		0.15-4.5mm	0.13-6.0mm
Minimum line width		4mils	3mils
Minimum Line gap		4mils	3mils
Outer layer copper thickness		1/3-4OZ	4-6OZ
Inner layer copper thickness		1/3-4oZ	4-6OZ
Min. finished hole size (Mechanical)		0.20mm	0.10mm
Min. finished hole size (laser hole)		0.05mm	0.05mm
Aspect ratio		10:1	10:1
Solder Mask Types and brand:		Nanya, Taiyo, Electra, Goats, Tamura	customer specify
Solder Mask Color		Gloss & matte green	Red, Black, Yellow, Blue, white
Impedance Control Tolerance		10%	5%
Surface Treatment	Flash Gold	Au:1-3U"	Au: 3U"
	Immersion Gold	Au:1-4U"	Au: 2-6U"
	Sn/PB HASL	Sn:100-1000U"	Sn: 200-800U"
	Leadfree HASL	Sn:100-1000U"	Sn: 200-800U"
	Immersion Silver	Ag: 1-8U"	Ag: 3-8U"
	OSP (Entek)	Thicknes: 0.2um	/
	Gold Finger	Au: 3-10U"	Au:10-60U"
	Hard Gold Plating	Au-3-10U"	Au:10-60U"
	Immsion Sn	Sn:1-40um	
V-Cut	V-cut degree:	30+/-5 degree	20,45, 60 Degree
	Outline Profile	Tol: +/-0.13mm	Tol: +/-0.10mm
Chamfer	The angle type of the chamfer:	20,30, 45 Degree	/
Plug via hole	Min. size can be plugged:	0.15mm	/
	Max. size can be plugged:	0.50mm	0.70mm
Largest NPTH hole size		6.50mm	Multi-hit(not limited)

Largest PTH hole size		6.50mm	Multi-hit(not limited)
Min. annular ring can be kept		6mils	4 mils
Min. distance between the IC pads can keep SM bridge		10mils	8mils
Min. SM bridge for green soldermask		4 mils	3 mils
Min. SM bridge for black soldermask		6mils	4mils
Tolerance of dimension size		Tol: +/-0.13mm	Tol: +/-0.10mm
Tolerance of board thickness		Tol: +/-10%	Tol: +/-5%
Tolerance of finished hole size		Tol: +/-0.08mm	Tol: +/-0.05mm